

The 21st Korean Conference on Semiconductors
제21회 한국반도체학술대회
February 24–26, 2014 / Hanyang University, Seoul, Korea

A. Interconnect & Package 분과

[TC2-A] Plating and Reliability

Date	Feb. 25, 2014 (Tue.)
Place	Room C / 제1공학관 401호 (# 401, Engineering Building I)

Session Chair: 김수현 교수(영남대학교),

- TC2-A-1 11:10-11:25 Cu Electrodeposition on Ru Seed Layer Prepared by Atomic Layer Deposition**
저자: Seunghoe Choe¹, Myung Jun Kim¹, Hyun Seok Ko², Young Kwang Kim³, Oh Joong Kwon³, and Jae Jeong Kim¹
소속: ¹School of Chemical and Biological Engineering, Seoul National University, ²Department of Material Science and Engineering, Incheon National University, ³Department of Energy and Chemical Engineering, Incheon National University
- TC2-A-2 11:25-11:40 Cu-Ag Superfilling for Damascene Metallization**
저자: Myung Jun Kim¹, Taeho Lim¹, Kyung Ju Park¹, Oh Joong Kwon², and Jae Jeong Kim¹
소속: ¹School of Chemical and Biological Engineering, Seoul National University, ²Department of Energy and Chemical Engineering, Incheon National University
- TC2-A-3 11:40-11:55 Real-Time Observation of Cu Electroless Deposition: Synergetic Suppression Effect of 2,2'-Dipyridyl and 3-N,N-Dimethylaminodithiocarbamoyl-1-propanesulfonic Acid**
저자: Taeho Lim, Myung Jun Kim, Kyung Ju Park, Kwang Hwan Kim, and Jae Jeong Kim
소속: School of Chemical and Biological Engineering, Seoul National University
- TC2-A-4 11:55-12:10 Effect of Pulsed Electric Field on Dielectric Breakdown in Damascene Cu Interconnects**
저자: Han-Wool Yeon¹, Jun-Young Song¹, Jang-Yong Bae², Yu-Chul Hwang², and Young-Chang Joo¹
소속: ¹Department of Materials Science & Engineering, Seoul National University, ²Memory Division, Samsung Electronics Co Ltd.
- TC2-A-5 12:10-12:25 Flexible Cu Barrier of PAH/PSS Laminar Structures using Layer-by-Layer (LbL) Method**
저자: Daekyun Jeong, Chiyong Lee, and Jaegab Lee
소속: Department of Advanced Materials Engineering, Kookmin University